

1 **ABSTRACT OF THE DISCLOSURE**

2 The invention encompasses polishing systems for polishing
3 semiconductive material substrates, and encompasses methods of cleaning
4 polishing slurry from semiconductive substrate surfaces. In one aspect,
5 the invention includes a method of cleaning a polishing slurry from a
6 substrate surface comprising: a) providing a substrate surface having a
7 polishing slurry in contact therewith; b) providing a liquid; c) injecting
8 a gas into the liquid to increase a total dissolved gas concentration in
9 the liquid; and d) after the injecting, providing the liquid against the
10 substrate surface to displace the polishing slurry from the substrate
11 surface. In another aspect the invention includes a method of polishing
12 a substrate surface comprising: a) providing a polishing slurry between
13 a substrate surface and a polishing pad; b) polishing the substrate
14 surface with the polishing slurry; and c) removing the polishing slurry
15 from the substrate surface, the removing comprising: i) providing a
16 liquid; ii) removing a first gas from the liquid to reduce a total
17 dissolved gas concentration in the liquid; iii) after the removing,
18 dissolving a second gas in the liquid to increase the total dissolved gas
19 concentration in the liquid; iv) after the dissolving, providing the liquid
20 between the substrate surface and the polishing pad to displace the
21 polishing slurry from the substrate surface.

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